Si Integrated Heat Spreader Considerations

Amkor's package enhancement can be embedded inside of a mold to expose the top surface to an external heat sink.

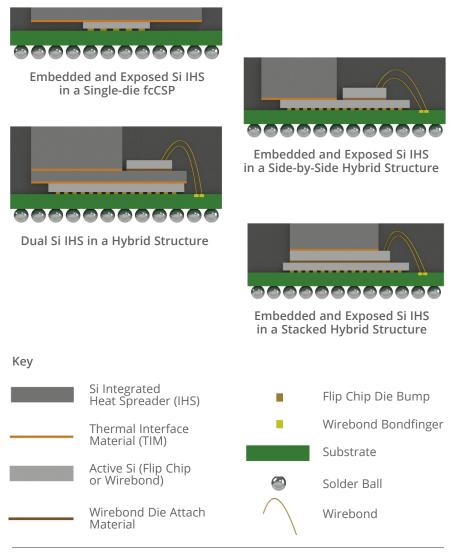
TECHNOLOGY SOLUTIONS

Si Integrated Heat Spreaders for fcCSP Packages

Si is an effective alternative to Cu as a heat spreader material.

- As a result of robust thermal conductivity and ease of processing, Si is an effective alternative to Cu as a heat spreader material
- Si Integrated Heat Spreaders (IHS) can be embedded inside the mold, while exposing its top surface to an external heat sink

Example constructions include:



Visit <u>amkor.com</u> or email <u>sales@amkor.com</u> for more information.

